

October 2003 Revised January 2004

FIN3385 • FIN3383 Low Voltage 28-Bit Flat Panel Display Link Serializers

General Description

The FIN3385 and FIN3383 transform 28 bit wide parallel LVTTL (Low Voltage TTL) data into 4 serial LVDS (Low Voltage Differential Signaling) data streams. A phase-locked transmit clock is transmitted in parallel with the data steam over a separate LVDS link. Every cycle of transmit clock 28 bits of input LVTTL data are sampled and transmitted.

These chipsets are an ideal solution to solve EMI and cable size problems associated with wide and high-speed TTL interfaces.

Features

- Low power consumption
- 20 MHz to 85 MHz shift clock support
- ±1V common-mode range around 1.2V
- Narrow bus reduces cable size and cost
- High throughput (up to 2.38 Gbps throughput)
- Internal PLL with no external component
- Compatible with TIA/EIA-644 specification
- Devices are offered in 48- and 56-lead TSSOP packages

Ordering Code:

Order Number	Package Number	Package Description				
FIN3383MTD	MTD56	56-Lead Thin Shrink Small Outline Package (TSSOP), JEDEC MO-153, 6.1mm Wide				
FIN3385MTD	MTD56	56-Lead Thin Shrink Small Outline Package (TSSOP), JEDEC MO-153, 6.1mm Wide				

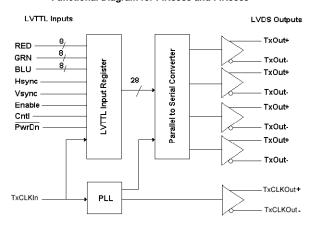
Devices also available in Tape and Reel. Specify by appending suffix letter "X" to the ordering code.

TABLE 1. Display Panel Link Serializers/De-Serializers Chip Matrix

Part	CLK Frequency	LVTTL IN	LVDS OUT	Package
FIN3385	85	28	4	56 TSSOP
FIN3383	66	28	4	56 TSSOP

Block Diagram

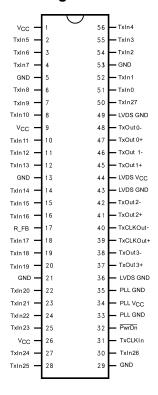
Functional Diagram for FIN3385 and FIN3383



Pin Descriptions

Pin Names	I/O Type	Number of Pins	Description of Signals
TxIn	ı	28/21	LVTTL Level Inputs
TxCLKIn	I	1	LVTTL Level Clock Input The rising edge is for data strobe.
TxOut+	0	4/3	Positive LVDS Differential Data Output
TxOut-	0	4/3	Negative LVDS Differential Data Output
TxCLKOut+	0	1	Positive LVDS Differential Clock Output
TxCLKOut-	0	1	Negative LVDS Differential Clock Output
R_FB	I	1	Rising Edge Clock (HIGH), Falling Edge Clock (LOW)
PwrDn	I	1	LVTTL Level Power-Down Input Assertion (LOW) puts the outputs in High Impedance state.
PLL V _{CC}	I	1	Power Supply Pin for PLL
PLL GND	I	2	Ground Pins for PLL
LVDS V _{CC}	I	1	Power Supply Pin for LVDS Outputs
LVDS GND	ı	3	Ground Pins for LVDS Outputs
V _{CC}	ı	3	Power Supply Pins for LVTTL Inputs
GND	I	5	Ground pins for LVTTL Inputs
NC			No Connect

Connection Diagram



Truth Table

	Inputs	Outputs		
TxIn	TxCLKIn	PwrDn (Note 1)	TxOut±	TxCLKOut±
Active	Active	Н	L/H	L/H
Active	L/H/Z	Н	L/H	X (Note 2)
F	Active	Н	L	L/H
F	F	Н	L	X (Note 2)
X	Х	L	Z	Z

H = HIGH Logic Level L = LOW Logic Level

Note 1: The outputs of the transmitter or receiver will remain in a High Impedance state until V_{CC} reaches 2V.

Note 2: TxCLKOut± will settle at a free running frequency when the part is powered up, PwrDn is HIGH and the TxCLKIn is a steady logic level (L/H/Z).

X = Don't Care

Z = High Impedance F = Floating

Absolute Maximum Ratings(Note 3)

 $\begin{array}{lll} \mbox{Power Supply Voltage (V_{CC})} & -0.3V \ \mbox{to } +4.6V \\ \mbox{TTL/CMOS Input/Output Voltage} & -0.5V \ \mbox{to } +4.6V \\ \mbox{LVDS Input/Output Voltage} & -0.3V \ \mbox{to } +4.6V \\ \mbox{LVDS Output Short Circuit Current (I_{OSD})} & \mbox{Continuous} \\ \mbox{Storage Temperature Range (T_{STG})} & -65^{\circ}{\rm C} \ \mbox{to } +150^{\circ}{\rm C} \\ \end{array}$

 $\label{eq:Storage Temperature Range Type} Storage Temperature Range (T_{STG}) \\ Maximum Junction Temperature (T_J) \\ 150^{\circ}C$

Lead Temperature (T_L)

(Soldering, 4 seconds) 260°C

ESD Rating (HBM, 1.5 k Ω , 100 pF)

 $\begin{tabular}{ll} I/O \ to \ GND &>&10.0 \ kV \\ All \ Pins &>&6.5 \ kV \\ ESD \ Rating \ (MM, 0\Omega, 200 \ pF) &>&400V \end{tabular}$

Recommended Operating Conditions

Supply Voltage (V_{CC}) 3.0V to 3.6V Operating Temperature (T_A)(Note 3) -10°C to +70°C

Maximum Supply Noise Voltage

 (V_{CCNPP}) 100 mV_{P-P} (Note 4)

Note 3: Absolute maximum ratings are DC values beyond which the device may be damaged or have its useful life impaired. The datasheet specifications should be met, without exception, to ensure that the system design is reliable over its power supply, temperature, and output/input loading variables. Fairchild does not recommend operation outside datasheet specifications

Note 4: 100mV V_{CC} noise should be tested for frequency at least up to 2 MHz. All the specification below should be met under such a noise.

DC Electrical Characteristics

Over supply voltage and operating temperature ranges, unless otherwise specified. (Note 5)

Symbol	Parameter	Test Conditions		Min	Тур	Max	Units
Transmitt	er LVTTL Input Characteristics	•					
V _{IH}	Input High Voltage			2.0		V _{CC}	V
V _{IL}	Input Low Voltage			GND		0.8	V
V _{IK}	Input Clamp Voltage	$I_{IK} = -18 \text{ mA}$			-0.79	-1.5	V
I _{IN}	Input Current	$V_{IN} = 0.4V \text{ to } 4.6V$			1.8	10.0	
		V _{IN} = GND		-10.0	0		μΑ
Transmitt	er LVDS Output Characteristics (Note 6)		•			•	
V _{OD}	Output Differential Voltage	$R_L = 100 \Omega$, See Figure 1		250	TBD	450	mV
ΔV_{OD}	V _{OD} Magnitude Change from Differential LOW-to-HIGH					35.0	mV
Vos	Offset Voltage			1.125	1.25	1.375	V
ΔV_{OS}	Offset Magnitude Change from Differential LOW-to-HIGH						mV
Ios	Short Circuit Output Current	V _{OUT} = 0V			-3.5	-5.0	mA
l _{OZ}	Disabled Output Leakage Current	$DO = 0V$ to 4.6V, $\overline{PwrDn} = 0V$			±1.0	±10.0	μΑ
Transmitt	er Supply Current		•				-
I _{CCWT}	28:4 Transmitter Power Supply Current	$\begin{array}{c} & 32.5 \text{ MHz} \\ \text{R}_{\text{L}} = 100 \ \Omega, & 40.0 \text{ MHz} \\ \text{See Figure 2} & 66.0 \text{ MHz} \end{array}$			31.0	49.5	mA
	for Worst Case Pattern (With Load)				32.0	55.0	
	(Note 7)				37.0	60.5	
			85.0 MHz		42.0	66.0	1
I _{CCPDT}	Powered Down Supply Current	PwrDn = 0.8V			10.0	55.0	μА
I _{CCGT}	28:4 Transmitter Supply Current		32.5 MHz		29.0	41.8	
	for 16 Grayscale (Note 7)	See Figure 11	40.0 MHz		30.0	44.0	mA
		(Note 8)	65.0 MHz		35.0	49.5	IIIA
			85.0 MHz		39.0	55.0	1

Note 5: All Typical values are at $T_A = 25^{\circ}C$ and with $V_{CC} = 3.3V$.

Note 6: Positive current values refer to the current flowing into device and negative values means current flowing out of pins. Voltage are referenced to ground unless otherwise specified (except ΔV_{OD} and V_{OD}).

Note 7: The power supply current for both transmitter and receiver can be different with the number of active I/O channels.

Note 8: The 16-grayscale test pattern tests device power consumption for a "typical" LCD display pattern. The test pattern approximates signal switching needed to produce groups of 16 vertical strips across the display.

AC Electrical Characteristics

Over supply voltage and operating temperature ranges, unless otherwise specified.

Symbol	Parameter	Test Conditions	Min	Тур	Max	Units
t _{TCP}	Transmit Clock Period		11.76	Т	50.0	ns
t _{TCH}	Transmit Clock (TxCLKIn) HIGH Time	See Figure 4	0.35	0.5	0.65	Т
t _{TCL}	Transmit Clock Low Time		0.35	0.5	0.65	Т
t _{CLKT}	TxCLKIn Transition Time (Rising and Failing)	(10% to 90%) See Figure 5	1.0		6.0	ns
t _{JIT}	TxCLKIn Cycle-to-Cycle Jitter				3.0	ns
t _{XIT}	TxIn Transition Time		1.5		6.0	ns
LVDS Trans	smitter Timing Characteristics	•			1	
t _{TLH}	Differential Output Rise Time (20% to 80%)	See Figure 2		0.75	1.5	ns
t _{THL}	Differential Output Fall Time (80% to 20%)	See Figure 3		0.75	1.5	ns
t _{STC}	TxIn Setup to TxCLNIn	O Figure 4 (f. OF MULE)	2.5			ns
t _{HTC}	TxIn Holds to TCLKIn	See Figure 4 (f = 85 MHz)	0			ns
t _{TPDD}	Transmitter Power-Down Delay	See Figure 7, (Note 9)			100	ns
t _{TCCD}	Transmitter Clock Input to Clock Output Delay	(T _A = 25°C and with V _{CC} = 3.3V)			5.5	
	Transmitter Clock Input to Clock Output Delay	See Figure 6	2.8		6.8	ns
Transmitte	r Output Data Jitter (f = 40 MHz) (Note 10)				I	
t _{TPPB0}	Transmitter Output Pulse Position of Bit 0		-0.25	0	0.25	ns
t _{TPPB1}	Transmitter Output Pulse Position of Bit 1	See Figure 9	a-0.25	а	a+0.25	ns
t _{TPPB2}	Transmitter Output Pulse Position of Bit 2	1	2a-0.25	2a	2a+0.25	ns
t _{TPPB3}	Transmitter Output Pulse Position of Bit 3	$a = \frac{1}{f \times 7}$	3a-0.25	3a	3a+0.25	ns
t _{TPPB4}	Transmitter Output Pulse Position of Bit 4		4a-0.25	4a	4a+0.25	ns
t _{TPPB5}	Transmitter Output Pulse Position of Bit 5		5a-0.25	5a	5a+0.25	ns
t _{TPPB6}	Transmitter Output Pulse Position of Bit 6	7	6a-0.25	6a	6a+0.25	ns
Transmitte	r Output Data Jitter (f = 65 MHz) (Note 10)				l	
t _{TPPB0}	Transmitter Output Pulse Position of Bit 0		-0.2	0	0.2	ns
t _{TPPB1}	Transmitter Output Pulse Position of Bit 1	See Figure 9	a-0.2	а	a+0.2	ns
t _{TPPB2}	Transmitter Output Pulse Position of Bit 2	1	2a-0.2	2a	2a+0.2	ns
t _{TPPB3}	Transmitter Output Pulse Position of Bit 3	$a = \frac{1}{f \times 7}$	3a-0.2	3a	3a+0.2	ns
t _{TPPB4}	Transmitter Output Pulse Position of Bit 4	7	4a-0.2	4a	4a+0.2	ns
t _{TPPB5}	Transmitter Output Pulse Position of Bit 5	7	5a-0.2	5a	5a+0.2	ns
t _{TPPB6}	Transmitter Output Pulse Position of Bit 6	7	6a-0.2	6a	6a+0.2	ns
Transmitte	r Output Data Jitter (f = 85 MHz) (Note 10)				1	
t _{TPPB0}	Transmitter Output Pulse Position of Bit 0		-0.2	0	0.2	ns
t _{TPPB1}	Transmitter Output Pulse Position of Bit 1	See Figure 9	a-0.2	а	a+0.2	ns
t _{TPPB2}	Transmitter Output Pulse Position of Bit 2	1	2a-0.2	2a	2a+0.2	ns
t _{TPPB3}	Transmitter Output Pulse Position of Bit 3	$a = \frac{1}{f \times 7}$	3a-0.2	3a	3a+0.2	ns
t _{TPPB4}	Transmitter Output Pulse Position of Bit 4	7	4a-0.2	4a	4a+0.2	ns
t _{TPPB5}	Transmitter Output Pulse Position of Bit 5	7	5a-0.2	5a	5a+0.2	ns
t _{TPPB6}	Transmitter Output Pulse Position of Bit 6	7	6a-0.2	6a	6a+0.2	ns
tucc	FIN3385 Transmitter Clock Out Jitter	f = 40 MHz		350	370	
330	(Cycle-to-Cycle)	f = 65 MHz		210	230	ps
	See Figure 10	f = 85 MHz		110	150	·

Note 9: Outputs of all transmitters stay in 3-STATE until power reaches 2V. Both clock and data output begins to toggle 10ms after V_{CC} reaches 3V and Power-Down pin is above 1.5V.

Note 10: This output data pulse position works for TTL inputs except the LVDS output bit mapping difference (see Figure 8). Figure 9 shows the skew between the first data bit and clock output. Also 2-bit cycle delay is guaranteed when the MSB is output from transmitter.

Note 11: This jitter specification is based on the assumption that PLL has a ref clock with cycle-to-cycle input jitter less than 2ns.

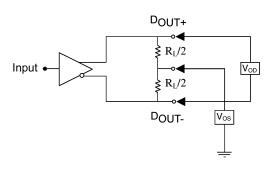
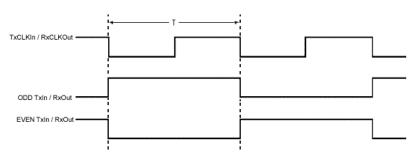


FIGURE 1. Differential LVDS Output DC Test Circuit

AC Loading and Waveforms



Note: The worst case test pattern produces a maximum toggling of digital circuits, LVDS I/O and LVTTL/CMOS I/O. Depending on the valid strobe edge of transmitter, the TxCLKIn can be either rising or falling edge data strobe.

FIGURE 2. "Worst Case" Test Pattern

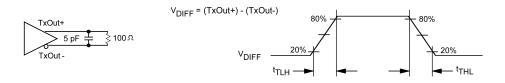


FIGURE 3. Transmitter LVDS Output Load and Transition Times

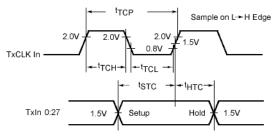


FIGURE 4. Transmitter Setup/Hold and HIGH/LOW Times (Rising Edge Strobe)

AC Loading and Waveforms (Continued)

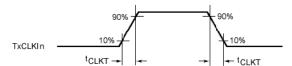


FIGURE 5. Transmitter Input Clock Transition Time

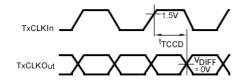


FIGURE 6. Transmitter Clock In to Clock Out Delay (Rising Edge Strobe)

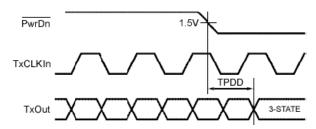
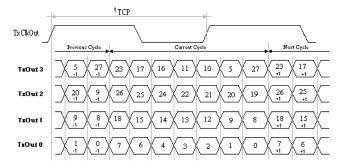


FIGURE 7. Transmitter Power-Down Delay



Note: The information in this diagram shows the relationship between clock out and the first data bit. A 2-bit cycle delay is guaranteed when the MSB is output from the transmitter.

FIGURE 8. 28 Parallel LVTTL Inputs Mapped to 4 Serial LVDS Outputs

AC Loading and Waveforms (Continued)

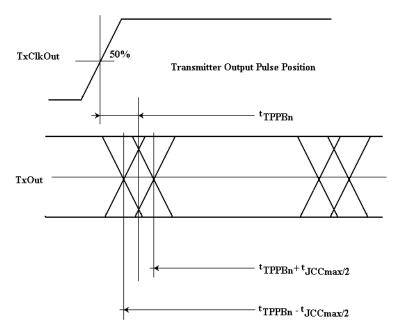
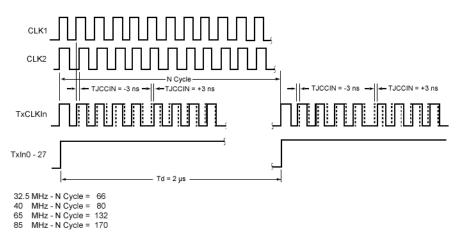


FIGURE 9. Transmitter Output Pulse Bit Position

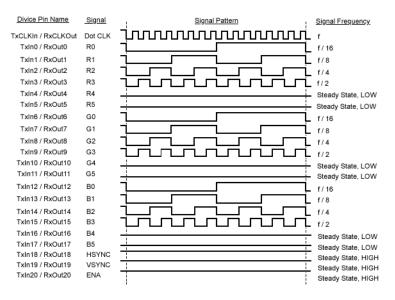


Note: This jitter pattern is used to test the jitter response (Clock Out) of the device over the power supply range with worst jitter ±3ns (cycle-to-cycle) clock input. The specific test methodology is as follows:

- Switching input data TxIn0 to TxIn20 at 0.5 MHz, and the input clock is shifted to left –3ns and to the right +3ns when data is HIGH.
- The ±3 ns cycle-to-cycle input jitter is the static phase error between the two clock sources. Jumping between two clock sources to simulate the worst
 case of clock edge jump (3 ns) from graphical controllers. Cycle-to-cycle jitter at TxCLK out pin should be measured cross V_{CC} range with 100mV noise
 (V_{CC} noise frequency <2 MHz).

FIGURE 10. Timing Diagram of Transmitter Clock Input with Jitter

AC Loading and Waveforms (Continued)



Note: The 16-grayscale test pattern tests device power consumption for a "typical" LCD display pattern. The test pattern approximates signal switching needed to produce groups of 16 vertical strips across the display.

FIGURE 11. "16 Grayscale" Test Pattern

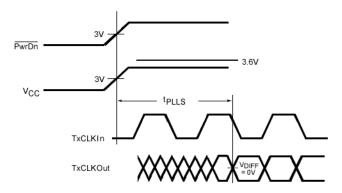
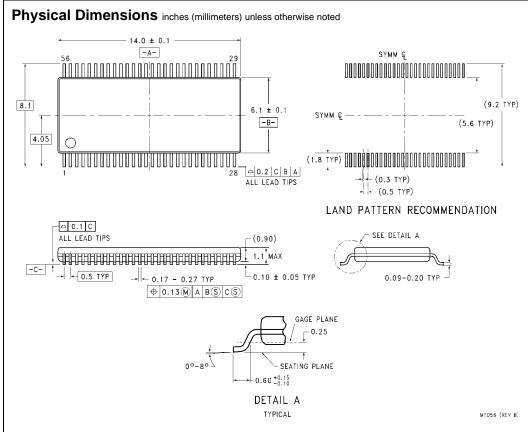


FIGURE 12. Transmitter Phase Lock Loop Time



56-Lead Thin Shrink Small Outline Package (TSSOP), JEDEC MO-153, 6.1mm Wide Package Number MTD56

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